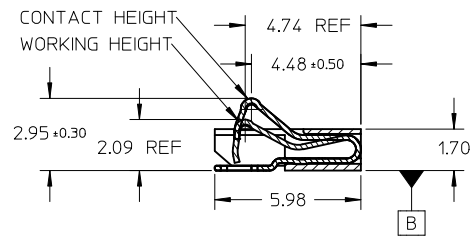
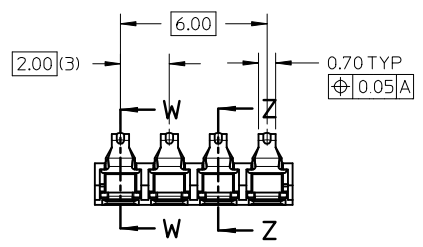
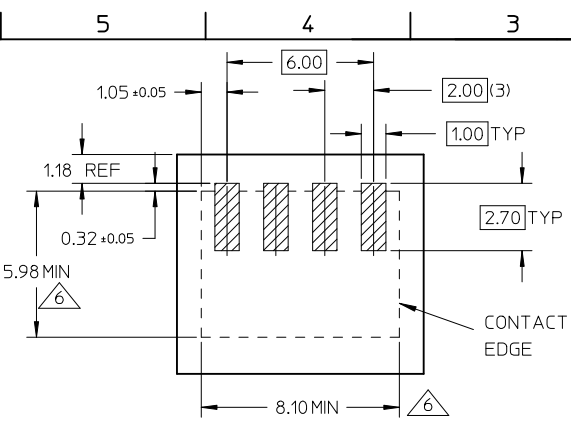
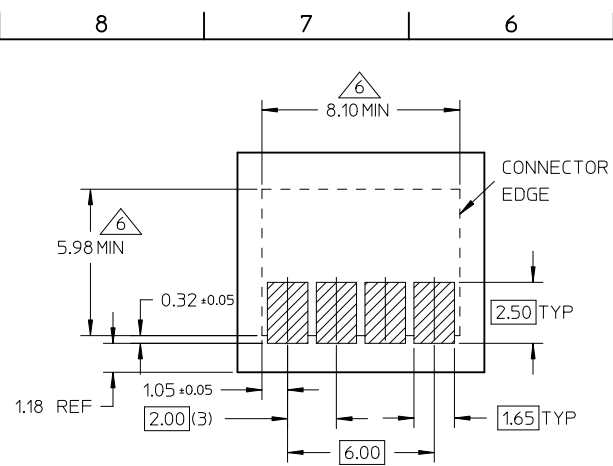
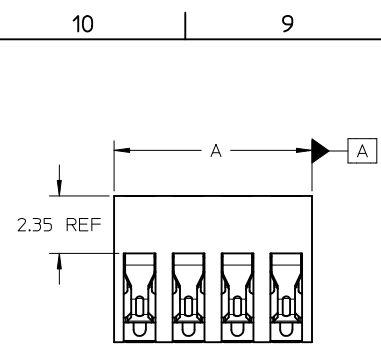
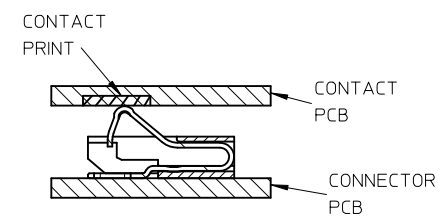


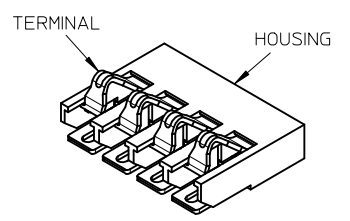
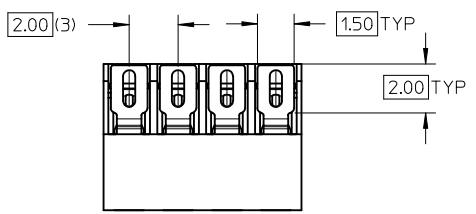
ASS. P/N	CKTS	A	B
47417-1001	2	4.10	2.00
47417-2001	3	6.10	4.00
47417-0001	4	8.10	6.00



SECTION Z-Z



SECTION W-W



- NOTE:
- MATERIAL:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC, COLOR :BLACK
TERMINAL: COPPER ALLOY.
 - FINISH:
CONTACT AREA: 0.75 MICRON GOLD MIN OVER 1.25 MICRON NICKEL MIN.
SOLDER AREA: GOLD FLASH (0.075~0.125 MICRON) OVER 1.25 MICRON NICKEL MIN. REST AREA: 1.25 MICRON NICKEL MIN.
 - COPLANARITY: 0.1 MAX AMONG THESE SOLDER TAILS.
 - PRODUCT SPECIFICATION: PS-47182-001
 - WORKING HEIGH: 2.10mm REF.
 - CONNECTOR KEEP-OUT ZONE

DRAWING UPDATE EC NO: S2012-0173 DRWN:LKCHEW 2011/09/16 CHKD: 2011/10/27 APPR: SHONG 2011/10/27 B	QUALITY SYMBOLS ▽ = 0 ▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY			
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.15 ± --- 1 PLACE ± 0.20 ± ---	DIMENSION STYLE MM ONLY	TITLE 2.0MM PITCH 4 CIRCUITS 0.7MM CONTACT WIDTH BATTERY CONNECTOR					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY LHSHEN	DATE 2006/02/18	CHECKED BY XU XIANG	DATE 2006/04/06	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-47417-001	SHEET NO. 1 OF 1
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							